

Abstract

The present invention provides a flexible wiring substrate which does not form anomalous deposition of tin-bismuth alloy plating, through prevention of exfoliation, during the process of plating with tin-bismuth alloy, of a solder resist layer. The invention also provides a method for producing the flexible wiring substrate.

The flexible wiring substrate 10 includes an insulating substrate 11, a wiring pattern 12 formed on a surface of the insulating substrate 11, and a solder resist layer 17 covering a surface of the wiring pattern 12 excluding at least terminal portions of the wiring pattern 12, at least a portion of the outermost surface of the wiring pattern 12 which is not covered with the solder resist layer 17 being provided with a tin-bismuth alloy plating layer 26, characterized in that the wiring pattern 12 comprises a base layer 21 formed of a conductor and that a first tin plating layer 24 is provided on the base layer 21 so as to extend under a region covered with the solder resist layer 17 and also under a region not covered with the solder resist layer 17.